ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

04 Jan 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16088

TITLE: NCN6001 expansion into XFAB-Lubbock

PROPOSED FIRST SHIP DATE: 04 Apr 2008

AFFECTED CHANGE CATEGORY(S): Subcontractor FAB site

AFFECTED PRODUCT DIVISION(S): Analog Power Management

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Shannon Riggs<Shannon.Riggs@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Matt Kas<Matt.Kas@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is a final process change notice to IPCN# 16055. The devices listed below have historically been fabricated at the XFAB facility in Erfurt, Germany, and are now qualified for fabrication at the XFAB facility in Lubbock, TX, USA. All XFAB facilities are certified ISO9001:2000 compliant. XFAB offers the same process technology in both fab locations; no die design or process changes were implemented for this activity. This change is considered a capacity expansion. At the expiration of this FPCN, the devices listed below may be processed at either qualified location.

Final Product/Process Change Notification #16088

RELIABILITY DATA SUMMARY:

Reliability Test Results:

Qualify by similarity to NCN6804MNR2G.

HTOL 1008 hrs @ 125C, 0/80, 0/80
HTSL 1008 hrs @ 150C, 0/80, 0/80
TC-PC -65to+150C 500 cycles, 0/80, 0/80
AC-PC TA=121C, RH@100% PSIG=15 for 96 hrs, 0/79, 0/79

Qualified to MSL1 @ 260C.

ELECTRICAL CHARACTERISTIC SUMMARY:

Characterization data is available upon request. Parametric and bench evaluations indicate material conforms to required performance in accordance with the datasheet specification.

CHANGED PART IDENTIFICATION:

There will be no changes to the topside part marking. Part traceability will be maintained in accordance with the ON Semiconductor policy.

Final Product/Process Change Notification #16088

AFFECTED DEVICE LIST

NCN6001DTBR2
NCN6001DTBR2G